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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	H8/300L
Core Size	8-Bit
Speed	8MHz
Connectivity	SCI
Peripherals	LCD, PWM, WDT
Number of I/O	71
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 75°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/df38344wv

15.2.5	LCD Characteristics	478
15.3	H8/3847R Group Absolute Maximum Ratings (Wide-range Specification)	480
15.4	H8/3847R Electrical Characteristics (Wide-range Specification)	481
15.4.1	Power Supply Voltage and Operating Range.....	481
15.4.2	DC Characteristics	484
15.4.3	AC Characteristics	489
15.4.4	A/D Converter Characteristics	494
15.4.5	LCD Characteristics.....	495
15.5	H8/3847S Group Absolute Maximum Ratings	497
15.6	H8/3847S Group Electrical Characteristics	498
15.6.1	Power Supply Voltage and Operating Range.....	498
15.6.2	DC Characteristics	500
15.6.3	AC Characteristics	505
15.6.4	A/D Converter Characteristics	510
15.6.5	LCD Characteristics.....	511
15.7	Absolute Maximum Ratings of H8/38347 Group and H8/38447 Group	513
15.8	Electrical Characteristics of H8/38347 Group and H8/38447 Group.....	514
15.8.1	Power Supply Voltage and Operating Ranges	514
15.8.2	DC Characteristics	517
15.8.3	AC Characteristics	526
15.8.4	A/D Converter Characteristics	530
15.8.5	LCD Characteristics.....	531
15.8.6	Flash Memory Characteristics.....	532
15.9	Operation Timing	535
15.10	Output Load Circuit	539
15.11	Resonator	540
15.12	Usage Note.....	541
Appendix A CPU Instruction Set.....		543
A.1	Instructions.....	543
A.2	Operation Code Map.....	551
A.3	Number of Execution States.....	553
Appendix B Internal I/O Registers		560
B.1	Addresses	560
B.2	Functions.....	564
Appendix C I/O Port Block Diagrams.....		630
C.1	Block Diagrams of Port 1.....	630
C.2	Block Diagrams of Port 2.....	634

2.5.7 System Control Instructions

Table 2.10 describes the system control instructions. Figure 2.9 shows their object code formats.

Table 2.10 System Control Instructions

Instruction	Size	Function
RTE		Returns from an exception-handling routine
SLEEP		Causes a transition from active mode to a power-down mode. See section 5, Power-Down Modes, for details.
LDC	B	Rs □ CCR, #IMM□ CCR Moves immediate data or general register contents to the condition code register
STC	B	CCR □ Rd Copies the condition code register to a specified general register
ANDC	B	CCR □ #IMM□ CCR Logically ANDs the condition code register with immediate data
ORC	B	CCR □ #IMM□ CCR Logically ORs the condition code register with immediate data
XORC	B	CCR □ #IMM□ CCR Logically exclusive-ORs the condition code register with immediate data
NOP		PC + 2 □ PC Only increments the program counter

Note: □ Size: Operand size

B: Byte

Bits 1 and 0: Subactive mode clock select (SA1 and SA0)

These bits select the CPU clock rate ($\phi_W/2$, $\phi_W/4$, or $\phi_W/8$) in subactive mode. SA1 and SA0 cannot be modified in subactive mode.

Bit 1 SA1	Bit 0 SA0	Description	
0	0	$\phi_W/8$	(initial value)
0	1	$\phi_W/4$	
1	*	$\phi_W/2$	

Note: * Don't care

5.2 Sleep Mode

5.2.1 Transition to Sleep Mode

1. Transition to Sleep (High-Speed) Mode

The system goes from active mode to sleep (high-speed) mode when a SLEEP instruction is executed while the SSBY and LSON bits in SYSCR1 are cleared to 0 and the MSON and DTON bits in SYSCR2 are also cleared to 0. In sleep mode CPU operation is halted but the on-chip peripheral functions. CPU register contents are retained.

2. Transition to Sleep (Medium-Speed) Mode

The system goes from active mode to sleep (medium-speed) mode when a SLEEP instruction is executed while the SSBY and LSON bits in SYSCR1 are cleared to 0, the MSON bit in SYSCR2 is set to 1, and the DTON bit in SYSCR2 is cleared to 0. In sleep (medium-speed) mode, as in sleep (high-speed) mode, CPU operation is halted but the on-chip peripheral functions are operational. The clock frequency in sleep (medium-speed) mode is determined by the MA1 and MA0 bits in SYSCR1. CPU register contents are retained.

The CPU may operate at a 1/2 state faster timing at transition to sleep (medium-speed) mode.

8.7.5 MOS Input Pull-Up

Port 6 has a built-in MOS pull-up function that can be controlled by software. When a PCR6 bit is cleared to 0, setting the corresponding PUCR6 bit to 1 turns on the MOS pull-up for that pin. The MOS pull-up function is in the off state after a reset.

PCR6 _n	0	0	1
PUCR6 _n	0	1	*
MOS input pull-up	Off	On	Off

(n = 7 to 0)

*: Don't care

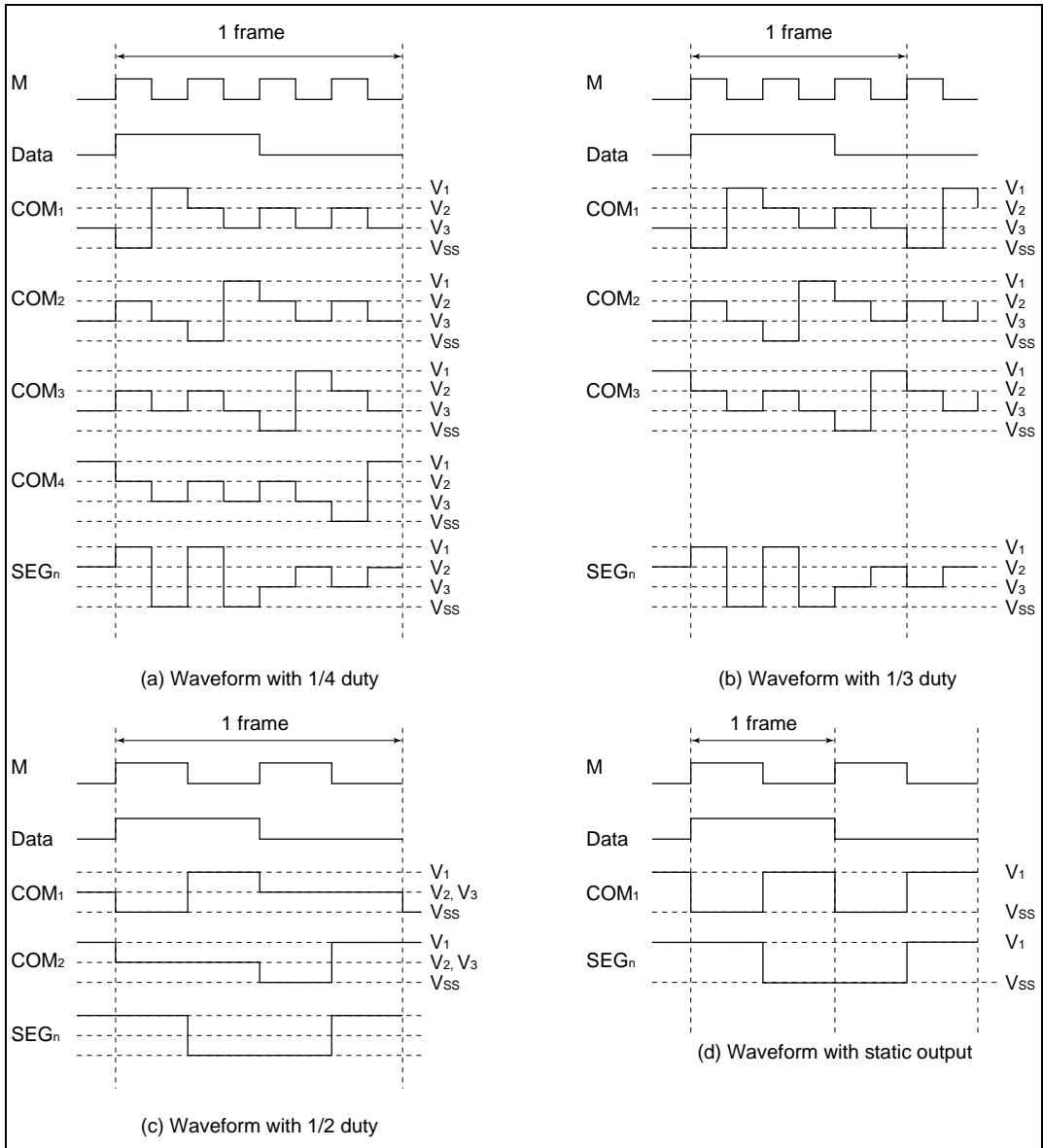
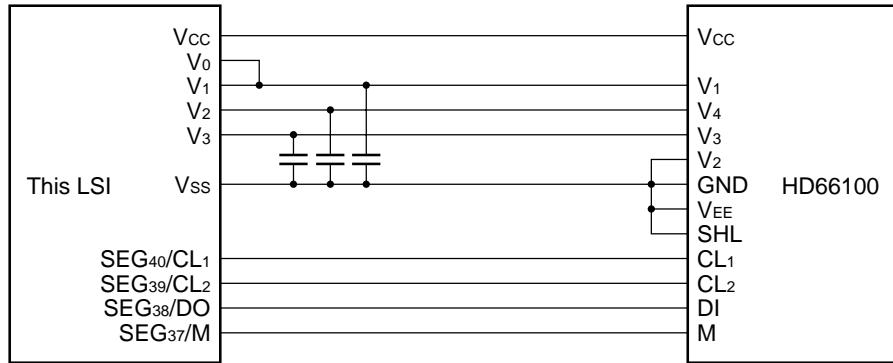
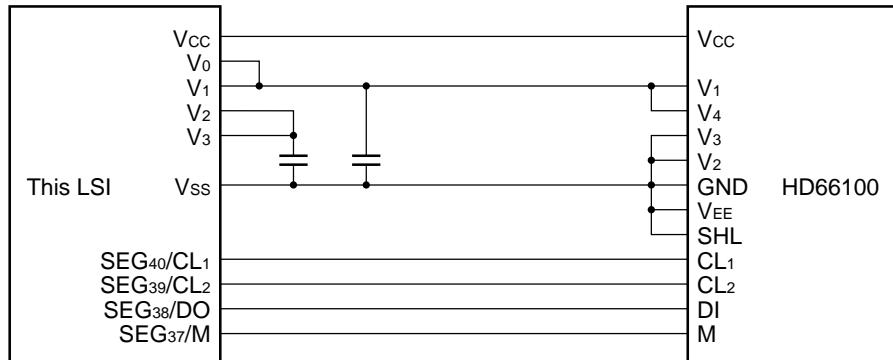


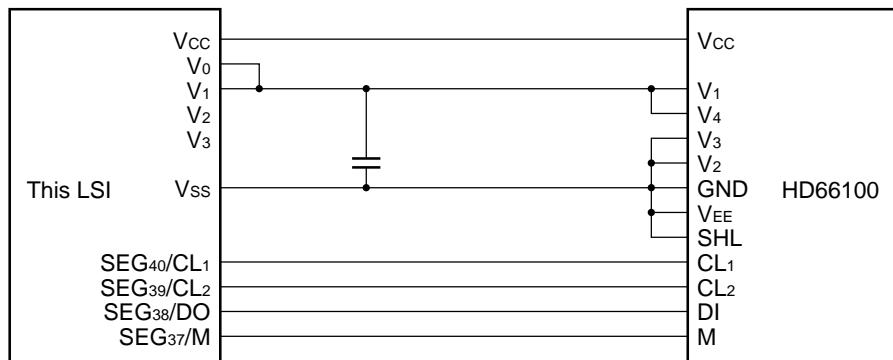
Figure 13.15 Output Waveforms for Each Duty Cycle (A Waveform)



(a) 1/3 bias, 1/4 duty or 1/3 duty



(b) 1/2 duty



(c) Static

Figure 13.18 Connection to HD66100

